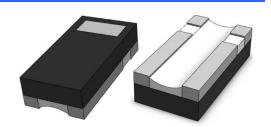
# **RLM0816T4F-4 Series Current Sensor Resistor (Lead / Halogen Free)**

## **Features / Applications:**

- Power rating is up to 1/2W
- Low TCR current sensor
- Resistors are ideal for all types of current sensing
- Metal foil construction; Excellent long-term stability
- Moisture sensitivity level: MSL 1
- RoHS compliant



### **Electrical Specifications:**

Characteristics <sup>1</sup>	F	eature
Power Rating <sup>2</sup>	1/2 W	
Resistance Value(mΩ)	0.75	1 to 5
Temperature Coefficient of Resistance(ppm/°C)	± 150	
Operation Temperature Range	-55°C to +155°C	
Maximum Working Voltage (V)	( P*R) <sup>1/2</sup>	

### Note:

- 1. For detailed information see table on page 3
- 2. For sensors operated at ambient temperature in excess of 70°C, the maximum load shall be derated in accordance with the following curve.

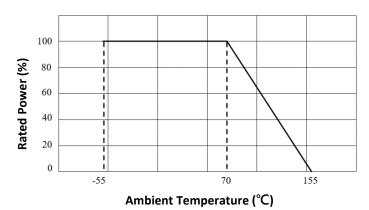
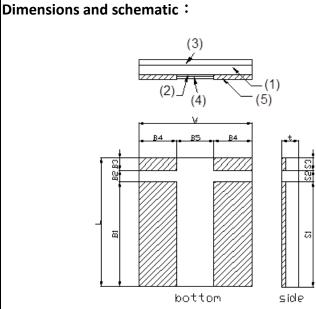


Figure 1. : Power Temperature Derating Curve

DOCUMENT: ST2G4-BNH

PAGE : 1 REVISION : A0

### **Outline Drawing:**



(1) Substrate

(2) Resistor : Cu alloy

(3) Protection coat:

Heat resistive epoxy resin (Black)

(4) Protection coat:

Heat resistive epoxy resin (White)

(5) Terminals: Sn (on Cu )

Resistance Range(mΩ)	L	W	<b>S1</b>	<b>S2</b>	<b>S3</b>	t
	0.80 ± 0.15	1.60 ± 0.20	1.10 ± 0.20	0.25 ± 0.10	0.25 ± 0.10	0.40 ± 0.15
0.75 to 5	B1	B2	В3	B4	B5	
	1.10 ± 0.20	0.25 ± 0.10	0.25 ± 0.10	0.20 ± 0.10	0.40 ± 0.20	

(Unit:mm)

## **Type Designation:**

RLM 0816T4F-4- \_\_\_\_\_ - \_\_NH

(3)

(1) (2)

(4)

(5)

Note:

(1) Series No.

(2) Size(T4F = 4 - terminal)

(3) Power Rating :4 = 1/2W

(4) Resistance value :  $0R5m = 0.5m\Omega$  ;  $R002 = 2m\Omega$  ;  $R010 = 10m\Omega$ 

(5) Tolerance: ±1%(F), ±2%(G), ±5%(J)

DOCUMENT: ST2G4-BNH

PAGE : 2 REVISION : A0



## **Available standard resistance values:**

Resistance Values	Tolerance				
	±0.5%	±1.0%	±2.0%	±5.0%	
0R75m		✓	✓	✓	
R001		✓	✓	✓	
R002		✓	✓	✓	
R003		✓	✓	✓	
R004		✓	✓	✓	
R005	✓	✓	✓	✓	

<sup>√ =</sup> available

Further values and tolerances on request.

DOCUMENT: ST2G4-BNH

PAGE : 3 REVISION : A0



## **Reliability Performance:**

Test Item	Condition of Test	Requirements
Short Time Overload	2.5 x Rated power for 5 seconds Refer to JIS C 5201-1 4.13	ΔR: ±1.0%
Thermal Cycling	-55 to 125℃ 100 cycles, 15 min at each extreme condition Refer to JIS C 5201-1 4.19	ΔR: ±1.0%
Low Temperature Storage	Kept at -55℃, 1000 hours Refer to JIS C 5201-1 4.23.4	ΔR: ±1.0%
Resistance to Soldering Heat	Dipped into solder at $260 \pm 5^{\circ}$ C for $10 \pm 1$ seconds Refer to JIS C 5201-1 4.18	
Load Life	Rated voltage for 1.5hours followed by a pause 0.5hour at 70 ± 3°C  Cycle repeated 1000 hours  Refer to JIS C 5201-1 4.25	ΔR: ±1.0%
Damp Heat with Load	40 ± 2°C with relative humidity 90% to 95%. D.C. rated voltage for 1.5 hours ON and 30 minutes OFF. Cycle repeated 1,000 hours Refer to JIS C 5201-1 4.24	ΔR: ±1.0%
High Temperature Exposure	Kept at 155°C for 1000 hours Refer to JIS C 5201-1 4.23.2	ΔR: ±1.0%
Solderability	Temperature of Solder : $245 \pm 5^{\circ}$ C Immersion Duration : $3 \pm 0.5$ second Refer to JIS C 5201-1 4.17	Uniform coating of solder cover minimum of 95% surface being immersed
Mechanical Shock	100 G's for 6milliseconds. 5 pulses Refer to JIS C 5201-1 4.21	ΔR: ±1.0%
Substrate Bending	Glass-Epoxy board thickness: 1.6mm Bending width: 2mm Between the fulcrums: 90mm Refer to JIS C 5201-1 4.33	ΔR: ±1.0%

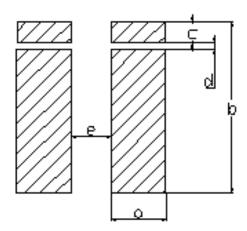
Note: Measurement at 24±4 hours after test conclusion for all reliability tests-parts.

DOCUMENT: ST2G4-BNH

PAGE : 4 REVISION : A0



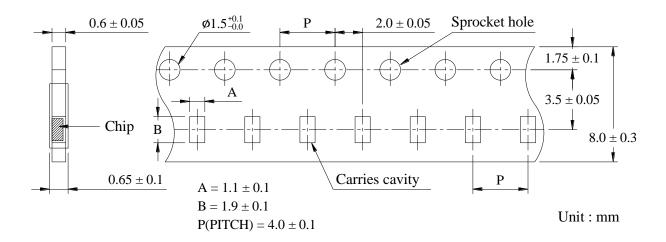
## **Recommend Solder Pad Dimensions:**



Dimensions (mm)	а	b	С	d	е
0.75 to 5 mΩ	0.4	1.9	0.4	0.2	0.35

## Packaging:

### Tape packaging dimensions:

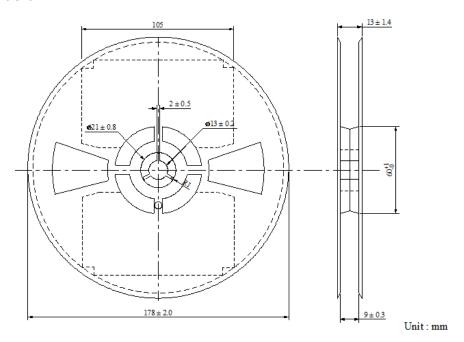


DOCUMENT: ST2G4-BNH

PAGE : 5 REVISION : A0



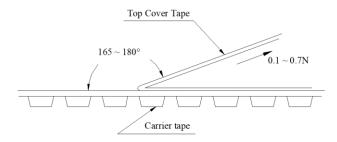
### Reel dimensions:



### Peel Strength of Top Cover Tape:

The peel speed shall be about 300mm/min.

The peel force of top cover tape shall between 0.1 to 0.7N



### Number of Taping:

5,000 pieces / reel

### **Label Marking:**

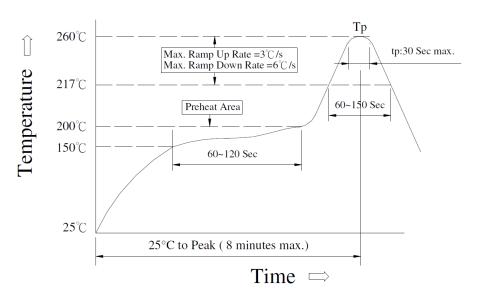
The following items shall be marked on the reel.

- (1) Type designation
- (2) Quantity
- (3) Manufacturing date code
- (4) Manufacturer's name
- (5) The country of origin

DOCUMENT: ST2G4-BNH

PAGE : 6 REVISION : A0

## **Recommend Soldering Conditions: :**



### Meet JEDEC-020D

### (1) Reflow Soldering Method:

Defless Calderine	Tp:255 to 260°C Max.30 seconds ( Tp )		
Reflow Soldering	217℃ 60 to 150 seconds		
Pre-Heat	150 to 200℃ 60 to 120 seconds		
Time 25℃ to peak temperature	8 minutes max		

(2) Soldering Iron Method: 350± 5°C max.3 seconds

DOCUMENT: ST2G4-BNH

PAGE : 7 REVISION : A0



### **Care Note:**

#### Care note for storage

- (1) Current sensor shall be stored in a environment where temperature and humidity must be controlled (temperature 5 to 40°C, humidity 30 to 80% RH). However, the humidity should be maintained as low as possible.
- (2) Current sensor shall not be stored under direct sunlight.
- (3) Current sensor shall be stored in condition without moisture, dust, any material defect solderability, or hazardous gas (i.e. Chlorination hydrogen, sulfurous acid gas, and sulfuration hydrogen)
- (4) The sensor can be stored for at least one year under the condition mentioned above.

#### Care note for operating and handling

- (1) It is necessary to protect the edge and protection coat of resistors from mechanical stress.
- (2) Handle with care when printing circuit board (PCB) is divided or fixed on support body, because bending of printing circuit board (PCB) mounting will make mechanical stress for resistors.
- (3) Resistors shall be used with in rated range shown in specification. Especially, if voltage more than specified value will be loaded to resistor, there is a case it will make damage for machine because of temperature rise depending on generating of heat, and increase resistance value or breaks.
- (4) In case that resistor is loaded a rated voltage, it is necessary to confirms temperature of a resistor and to reduce a load power according to load reduction curve, because a temperature rise of a resistor depends on influence of heat from mounting density and neighboring element.
- (5) Observe Limiting element voltage and maximum overload voltage specified in each specification
- (6) If there is possibility that a large voltage (pulse voltage, shock voltage) charge to resistor, it is necessary that operating condition shall be set up before use.

**DOCUMENT: ST2G4-BNH** 

PAGE: 8 REVISION: A0